

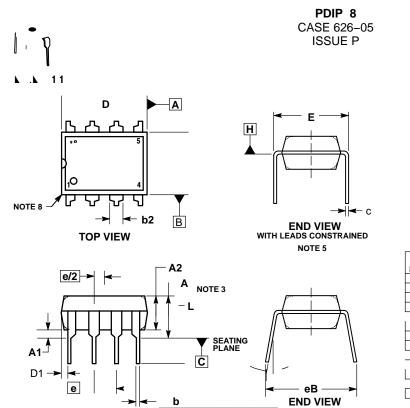
TH



THIS DEVICE PLEASE







0.010

SIDE VIEW

CAMBM

NOTE 6

	INCHES			
DIM	MIN	MAX		
Α		0.210		
A1	0.015			
A2	0.115	0.195	2.92	4.95
b	0.014	0.022		
С	0.008	0.014		
D	0.355	0.400		
D1	0.005			
Е	0.300	0.325		
е	0.100 BSC			
L	0.115	0.150	2.92	3.81
		0		0

DATE 22 APR 2015

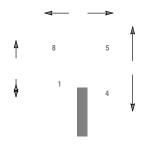
GENERIC **MARKING DIAGRAM***

Ь	Д	Д	1		
XXXXXXXXXX					
Þ	AWL YYWWG				
0					
Ţ	Ъ	Ъ	Г		

- XXXX = Specific Device Code
- = Assembly Location А
- WL = Wafer Lot
- = Year YΥ
- WW = Work Week G
 - = Pb-Free Package



DATE 16 FEB 2011



SEATING PLANE



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